

**Amendments to the Specification:**

Please replace the text appearing on page 6, line 10 through page 7, line 11 with the following text:

This and other objects are ~~solved~~achieved by an LGA socket contact that has a base plate with side walls. A resilient contact extends parallel to the base plate. The resilient contact is attached to at least one of the side walls of the base plate by a curved section angled approximately 180 degrees from the at least one side wall. The resilient contact has a free end for contacting a contact pad. A board terminal extends from a lower end of the base plate for connection to a circuit board.

This and other objects are further ~~solved~~achieved by a land grid array socket contact that is formed from a metal plate and has a base plate with side walls. A resilient contact extends parallel to the base plate and is attached to at least one of the side walls of the base plate by a curved section so that a height of the curved section and the resilient contact in a direction perpendicular to the base plate is substantially twice the thickness of the metal plate. The resilient contact has a free end for contacting a contact pad. A board terminal extends from a lower end of the base plate for connection to a circuit board.

This and other objects are still further ~~solved~~achieved by a land grid array socket contact that has a base plate and a resilient contact that extends from an upper end of the base plate. The resilient contact has an elongated slit substantially in a center of the resilient contact with respect to a direction of width. The resilient contact has a free end for contacting a contact pad. A board terminal extends from a lower end of the base plate for connection to a circuit board.

Please replace the text appearing on page 17, line 1 through page 18, line 3 with the following text:

The LGA socket (not shown) is mounted on a circuit board (not shown) by soldering the solder balls (not shown) disposed on the solder ball attachment paddles 61 of the respective contacts 51 to contact pads (not shown) on the circuit board (now shown). When the IC package (not shown) is mounted on the LGA socket (not shown) from above, the contact pads (not shown) disposed on the IC package (not shown) contact the contact portions 59 of the respective contacts 51 and push the contact portions 59 downward so that the second elastic plate portions 58, the first elastic plate portions 57, and the elastic plate portions 54 undergo elastic deformation. The contact pads (not shown) of the IC package (not shown) and the contact pads (not shown) of the circuit board (not shown) are thereby electrically connected to each other. Since the flexibility of the elastic plate portions 54 is increased as a result of the formation of the slits 55 that extend in the vertical direction in the approximate central portions of the elastic plate portions 54 with respect to the direction of width, the elastic plate portions 54 easily undergo elastic deformation. Since the elastic plate portions 54, the first elastic plate portions 57, and the second elastic plate portions 58 that are located above the base plates 52 ~~and that~~ are anchored to the housing (not shown) all undergo elastic deformation, the spring length may be made longer so that the amount of displacement of the resilient contacts 56 may be increased. Since the spring length may be made longer, plastic deformation does not occur even if the plate thickness of the contacts 51 is increased, because the connection resistance may be correspondingly reduced.

Please replace the text appearing on page 29, lines 3-16 with the following text:

~~A land grid array socket contact structured so that the size of a resilient contact in a direction perpendicular to a base plate in a vicinity of a root of the resilient contact is minimized so that an arrangement pitch in this direction may be reduced and the resilient contact may be displaced by a large amount to minimize connection resistance.~~ A The land grid array socket contact has a base plate with side walls. A resilient contact that extends parallel to the a base plate. ~~The resilient contact~~ and is attached to at least one of the side walls of the base plate by a curved section angled approximately 180 degrees from the at least one side wall. The resilient contact has a free end for contacting a contact pad. A board terminal extends from a lower end of the base plate for connection to a circuit board. In another embodiment, the land grid array socket contact has a resilient contact extending from an upper end of a base plate. The resilient contact has an elongated slit substantially in a center of the resilient contact with respect to a direction of width and a free end for contacting a contact pad. A board terminal extends from a lower end of the base plate for connection to a circuit board.